Product Change Notification / ALAN-03LXTT422

Date:

04-Mar-2022

Product Category:

Wireless Modules

PCN Type:

Manufacturing Change

Notification Subject:

eSign E000093606 Final Notice: Announcing the release of a new catalog part number (CPN) convention to support the use of silicon revision A1 and software tool to support silicon revision B0 for WFI32E01 modules

Affected CPNs:

ALAN-03LXTT422_Affected_CPN_03042022.pdf
ALAN-03LXTT422_Affected_CPN_03042022.csv

Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Announcing the release of a new catalog part number (CPN) convention to support the use of silicon revision A1 and software tool to support silicon revision B0 for WFI32E01 modules.

Note: The release of silicon die revision B0 was previously announced in**PCN SYST-20UNZO493.**

Pre and Post Change Summary:

	Pre-Change	**Post Change**
CPN	WFI32E01PC-I WFI32E01PE-I WFI32E01UC-I WFI32E01UE-I	WFI32E01PC-IA1 WFI32E01PE-IA1 WFI32E01UC-IA1 WFI32E01UE-IA1
Silicon Revision	A1 or B0	A1
Software for Silicon Rev A1	Existing CSP versions that are older than v3.10.0	Not Applicable
Software for Silicon Rev B0	MPLAB® Harmony 3 Chip Support Package (CSP) v3.10.0 Binary images built with CSP versions earlier than v3.10.0 must not be used with silicon revision (B0) and modules containing B0. Version 3.10.0 may be used with silicon version A1. https://github.com/Microchip-MPLAB-Harmony/csp/blob/master/release_notes.md	MPLAB® Harmony 3 Chip Support Package (CSP) v3.10.0 Binary images built with CSP versions earlier than v3.10.0 must not be used with silicon revision (B0) and modules containing B0. Version 3.10.0 may be used with silicon version A1. https://github.com/Microchip-MPLAB-Harmony/csp/blob/master/release_notes.md

Impacts to Data Sheet: None

Change Impact None

Reason for Change: Offer customers an option to remain on silicon rev A1 and existing software and to ensure customers may smoothly migrate their software to new silicon revision B0 by providing instructions for the MPLAB® Harmony 3 Chip Support Package (CSP) v3.10.0. This software is required if the module includes silicon revision B0.

Binary images built with CSP versions earlier than v3.10.0 must not be used with silicon revision (B0) and modules containing B0. Version 3.10.0 may be used with silicon version A1.

Details about MPLAB® Harmony 3 Chip Support Package (CSP) can be found in below link:

https://github.com/Microchip-MPLAB-Harmony/csp/blob/master/release_notes.md

Change Implementation Status: In Progress

Estimated First Ship Date: March 15, 2022 (date code: 2212)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	March 2022				
Workweek	10	11	12	13	14
Final PCN Issue Date	X				
Estimated Implementation Date			X		

Method to Identify Change: Catalog part number

Qualification Report: Not Applicable.

Revision History: March 04, 2022: Issued final notice.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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